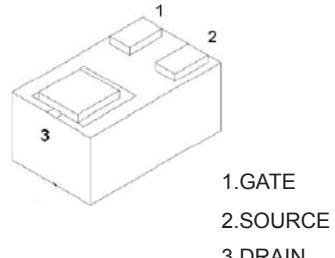


**N-Channel MOSFET****2KK6009DFN****■ Features**

- $V_{DS(V)} = 20$  V
- $I_D = 0.75$  A
- $R_{DS(ON)}$  (at  $V_{GS} = 4.5$  V) < 380 mΩ
- $R_{DS(ON)}$  (at  $V_{GS} = 2.5$  V) < 450 mΩ
- $R_{DS(ON)}$  (at  $V_{GS} = 1.8$  V) < 800 mΩ

**DFN1006-3****■ Absolute Maximum Ratings ( $T_a = 25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	20	V
Gate-Source Voltage	$V_{GS}$	$\pm 10$	
Continuous Drain Current (Note 1)	$I_D$	0.75	A
Pulsed Drain Current ( $t_p=10\mu\text{s}$ )	$I_{DM}$	1.8	
Power Dissipation (Note 1)	$P_D$	100	mW
Thermal Resistance, Junction-to-Ambient (Note 1)	$R_{\theta JA}$	1250	°C/W
Junction Temperature	$T_J$	150	°C
Storage Temperature Range	$T_{STG}$	-55 to 150	

Note 1. Surface mounted on FR4 board using the minimum recommended pad size.

**N-Channel MOSFET****2KK6009DFN****■ Electrical Characteristics ( $T_a = 25^\circ\text{C}$  unless otherwise specified)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>STATIC PARAMETERS</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$I_D = 250 \mu\text{A}, V_{GS} = 0\text{V}$	20			V
Zero Gate Voltage Drain Current	$I_{DS(on)}$	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}$			1	$\mu\text{A}$
Gate to Source Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{V}, V_{GS} = \pm 10\text{V}$			$\pm 20$	$\mu\text{A}$
Gate to Source Threshold Voltage (Note 2)	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	0.35		1.1	V
Static Drain-Source On-Resistance (Note 2)	$R_{DS(on)}$	$V_{GS} = 4.5\text{V}, I_D = 0.65\text{A}$			380	$\text{m}\Omega$
		$V_{GS} = 2.5\text{V}, I_D = 0.55\text{A}$			450	
		$V_{GS} = 1.8\text{V}, I_D = 0.45\text{A}$			800	
Forward Transconductance (Note 2)	$g_{FS}$	$V_{DS} = 10\text{V}, I_D = 0.8\text{A}$		1.6		S
Diode Forward Voltage	$V_{SD}$	$V_{GS} = 0\text{V}, I_S = 0.15\text{A}$			1.2	V
<b>DYNAMIC PARAMETERS (Note 4)</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{V}, V_{DS} = 16\text{V}, f = 1\text{MHz}$		79	120	$\text{pF}$
Output Capacitance	$C_{oss}$			13	20	
Reverse Transfer Capacitance	$C_{rss}$			9	15	
<b>SWITCHING PARAMETERS (Note 4)</b>						
Turn-On Delay Time (Note 3)	$t_{d(on)}$	$V_{GS} = 10\text{V}, V_{DD} = 4.5\text{V}, I_D = 0.5\text{A}, R_{GEN} = 10\Omega$		6.7		$\text{ns}$
Turn-On Rise Time (Note 3)	$t_r$			4.8		
Turn-Off Delay Time (Note 3)	$t_{d(off)}$			17.3		
Turn-Off Fall Time (Note 3)	$t_f$			7.4		

Notes:

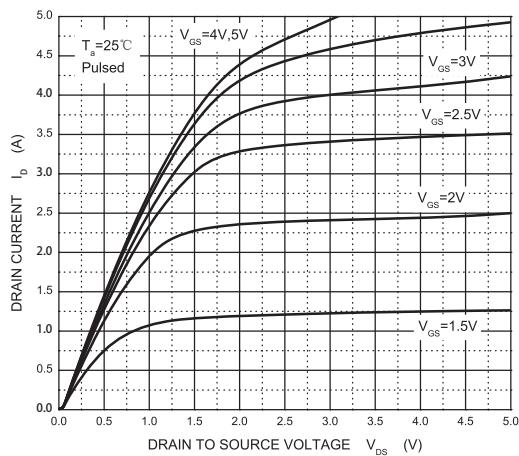
2. Pulse Test : Pulse width=300  $\mu\text{s}$ , duty cycle  $\leq 2\%$ .
3. Switching characteristics are independent of operating junction temperatures.
4. Guaranteed by design, not subject to producing.

**■ Marking**

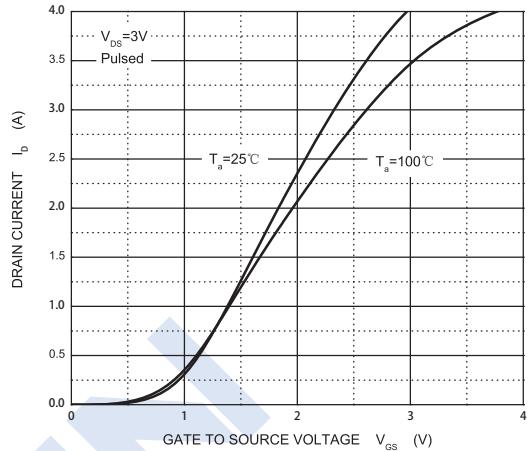
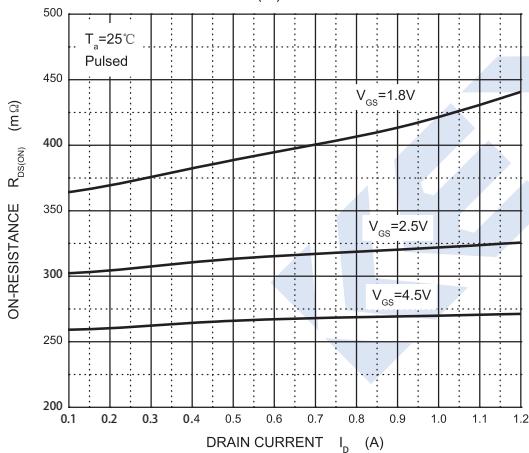
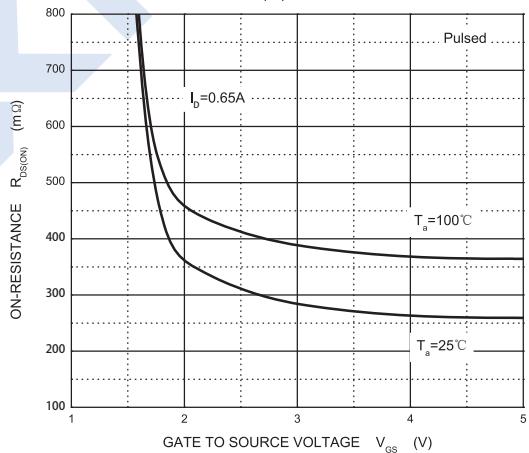
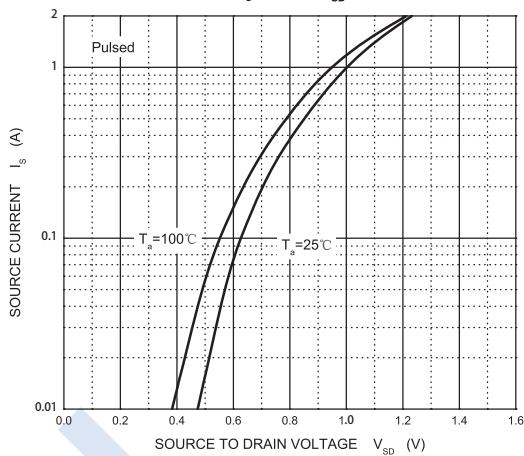
Marking	A
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**N-Channel MOSFET****2KK6009DFN****■ Typical Characteristics**

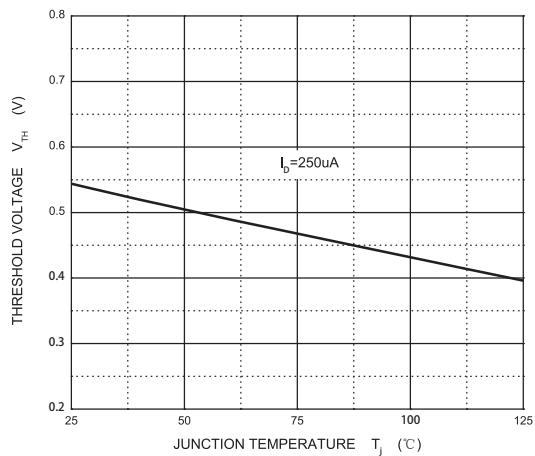
Output Characteristics

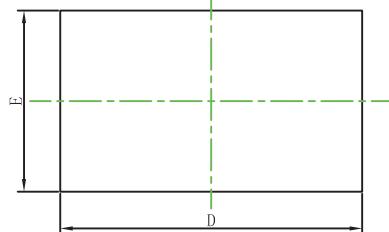


Transfer Characteristics

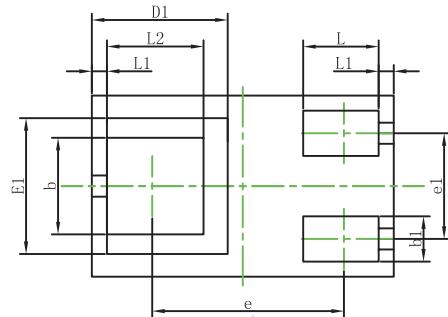
 $R_{DS(ON)}$  —  $I_D$  $R_{DS(ON)}$  —  $V_{GS}$  $I_S$  —  $V_{SD}$ 

Threshold Voltage

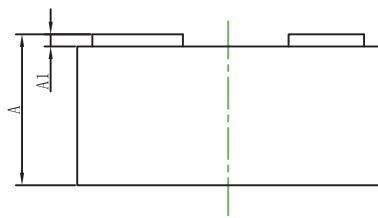


**N-Channel MOSFET****2KK6009DFN****■ DFN1006-3 Package Outline Dimensions**

TOP VIEW

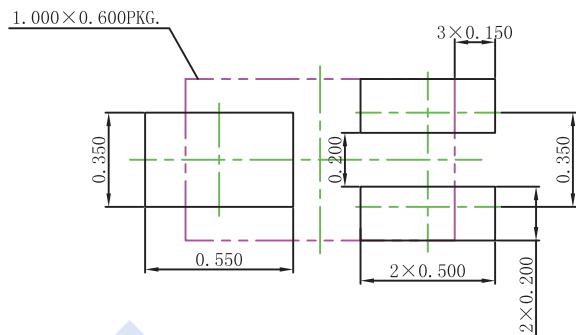


BOTTOM VIEW



SIDE VIEW

Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.450	0.550	0.018	0.022
A1	0.010	0.100	0.000	0.004
D	0.950	1.050	0.037	0.041
E	0.550	0.650	0.022	0.026
D1	0.450REF.		0.018REF.	
E1	0.450REF.		0.018REF.	
b	0.270	0.370	0.011	0.015
b1	0.100	0.200	0.004	0.008
e	0.635REF.		0.025REF.	
e1	0.300	0.400	0.012	0.016
L	0.200	0.300	0.008	0.012
L1	0.050REF.		0.002REF.	
L2	0.270	0.370	0.011	0.015

**■ DFN1006-3 Suggested Pad Layout****Note:**

1. Controlling dimension:in millimeters.
- 2.General tolerance: $\pm 0.050\text{mm}$ .
- 3.The pad layout is for reference purposes only.